Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Please amend claims 15, 18, 19 and 20 as shown.

Claims 1-14 (cancelled).

15. (currently amended): A laminate, comprising:

a conductive metal layer for an electronic circuit; and

a porous insulating film,

wherein the conductive metal layer is laminated on one or both sides of the porous insulating film either directly or via a heat resistant adhesive layer, and

wherein the porous insulating film comprises a highly heat resistant resin film having a fine porous structure with

a mean pore size of 0.05 ~~0.01~~ to 5 μm in at least the center of the film,

a void volume of 15 to 80%, and

a heat shrinkage factor of no greater than ±1% as measured at 105° C for 8 hours.

16. (previously presented): The laminate according to claim 15, wherein an inorganic, organic or metal substrate is laminated on one side of the porous insulating film and the conductive metal layer is laminated on the other side.

17. (previously presented): The laminate according to claim 16, wherein the inorganic or metal substrate and the conductive metal layer are each laminated to the porous insulating film via a heat resistant adhesive layer.

18. (currently amended): The laminate according to claim 15, wherein the mean pore size is 0.05 ~~0.01~~ to 2 μm.

19. (currently amended): The laminate according to claim 15, wherein the mean pore size is 0.05 ~~0.01~~ to 1 μm.

20. (currently amended): The laminate according to claim 15, wherein the heat resistant resin film contains fine continuous channels with a mean pore size of 0.05 ~~0.01~~ to 5 μm in the center and both surfaces of the film that reach to both surfaces of the film in a nonlinear fashion.

21. (previously presented): The laminate according to claim 15, wherein the void volume is 30 to 80%.

22. (previously presented): The laminate according to claim 15, wherein the porous insulating film has a thickness of 5 to 150 μm.

23. (previously presented): The laminate according to claim 15, wherein the fine porous structure consists of fine continuous pores.

24. (previously presented): The laminate according to claim 15, wherein the porous insulating film is fabricated by a film casting method.

25. (previously presented): The laminate according to claim 15, wherein the porous insulating film has a permittivity of no greater than 2.5.

26. (previously presented): The laminate according to claim 15, wherein the highly heat resistant resin film is a polyimide film.

27. (previously presented): The laminate according to claim 15, wherein the porous structure has fine continuous pores reaching to both surfaces.

28. (previously presented): The laminate according to claim 15, wherein the porous structure has
a void volume of 30-80%,
a pore size of no greater than 10 μm,
a film thickness of 5 to 100 μm,
a gas permeability of from 30 sec/100 cc to 2000 sec/100 cc, and
a heat resistance temperature of at least 200° C.

29. (previously presented): The laminate according to claim 15, wherein the porous structure has a dense layer on both surfaces of the film.

30. (previously presented): The laminate according to claim 15, wherein the porous insulating film comprises a polyimide, comprising

a tetracarboxylic acid component that includes a biphenyltetracarboxylic acid, and

an aromatic diamine component that includes paraphenylenediamine or diaminodiphenylether.

31. (previously presented): The laminate according to claim 15, wherein the porous insulating film has a dielectric constant of no greater than 2.5 as measured at a frequency of 1000 Hz or 10 MHz.